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## Micro component assembly machine

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### Abstract

A machine for automatically placing chips or similar micro-electronic components on a substrate carried on an X-Y type table, the machine having means to supply components, means to convey the components, means to transfer the components from the supply source to the conveyor, the conveyor transporting the components to a placement head located above the substrate to place the component on the substrate. The machine can also include a station for applying an adhesive or similar means on the substrate to adhere the component on the substrate.

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